

A study on the high rate deposition of CrN_x films with controlled microstructure by magnetron sputtering

Kyung H. Nam*, Min J. Jung, Jeon G. Han

Plasma Applied Materials Laboratory, Department of Advanced Materials, Sung Kyun Kwan University, 300 Chunchun-dong, Jangan-ku, Suwon 440-746, South Korea

Abstract

High rate deposition of CrN_x films with control of microstructure was carried out by magnetron sputtering. For these purposes, the deposition processes parameters were varied: N₂ flow rate and especially substrate bias voltage, duty cycle and frequency using a pulsed DC power supply. The microstructure was analyzed by X-ray diffraction (XRD) and scanning electron microscopy (SEM), and mechanical properties were evaluated by a microhardness test and adhesion test. The maximum deposition rate for CrN_x compound films could be reached to nearly 90% compared with that for pure Cr coating due to the increase of ionization efficiency caused by a negative-pulsed DC bias. As N₂ flow rate is increased, the microstructure of CrN_x films was changed from Cr + Cr₂N to CrN. Also, a phase transformation occurred between Cr₂N + CrN multi-phase and CrN mono-phase by control of a negative DC and/or pulsed DC bias voltage, duty cycle and frequency. Microhardness for CrN_x films were measured to be up to 1600 kg/mm² and the maximum hardness value of 2250 kg/mm² was obtained for CrN_x film deposited with a N₂ flow rate of 20 sccm at a negative DC bias of –100 V. © 2000 Elsevier Science B.V. All rights reserved.

Keywords: CrN_x; Magnetron; Deposition rate; Microstructure; Pulsed DC bias

1. Introduction

High rate deposition processes such as high current arc, laser arc, hollow cathode discharge ion plating and magnetron sputtering methods have been developed for cost effective industrial applications [1–3]. Especially magnetron sputtering is emerging as a very efficient method for the synthesis of high rate deposited dense films. In the early years of the 1990s a deposition rate of 1 ~ 3 μm/min has been reached using an unbalanced magnetron, but these have been restricted to pure metal films such as Cu, Ag, etc., of high sputtering yield. Overcoming a poisoning effect between metallic targets (Ti, Cr, etc.) and reactive gases (N₂, O₂, etc.), high rate deposition of reactively sputtered

nitride and oxide films by reactive magnetron sputtering have been realized to the deposition rate of 60 ~ 70% compared with that of pure metals by precise partial pressure control of the reactive gas [4,5]. In the mean time, the correlations between process parameters, microstructure and film properties have also been intensively studied to ensure the reproducibility of films with pre-defined properties [6–8]. In case of nitride films, particularly, it has been reported that the main parameters controlling the film microstructure are deposition temperature, N₂ partial pressure and bias voltage [6,7,9].

In this study, an unbalanced magnetron sputtering was employed to synthesize CrN_x films for high rate deposition with a control of microstructure. Deposition processes for such purpose were varied with N₂ flow rate and specially substrate bias voltage, duty cycle and frequency using pulsed DC power supply. The microstructure was analyzed by X-ray diffraction (XRD)

* Corresponding author. Tel.: +82-331-290-7381; fax: +82-331-290-7386.

E-mail address: khnam@nature.skku.ac.kr (K.H. Nam).

and scanning electron microscopy (SEM), and mechanical properties were evaluated by microhardness and adhesion tests.

2. Experimental details

2.1. Film deposition

CrN_x films were deposited on AISI 304 stainless steel and Si wafers by magnetron sputtering of a rectangular Cr target with a moving magnet designed for high erosion efficiency, in our laboratory. The discharges of this magnetron, which are elliptically shaped with the longer axis perpendicular to the longer axis of the target, are generated by separated magnetic units placed behind the target. Non-sputtered regions inside the individual racetracks are eliminated by the simultaneous sweeping of all magnetron discharges along the longer axis of the target, which is achieved by moving the magnetic means behind the target. All specimens were cleaned following conventional cleaning process prior to deposition. The deposition process was performed in the following steps: (1) radiation heating; (2) DC glow discharge cleaning in an Ar atmosphere for 10 min; (3) sputter deposition of a 0.2 μm Cr interlayer film; (4) deposition of CrN_x films at various conditions listed in Table 1.

2.2. Evaluation of films

For the evaluation of phase and texture formation for CrN_x films XRD analyses were performed with an incident angle of 3°. By using SEM fracture cross-section

Table 1
Conditions for CrN_x coating process

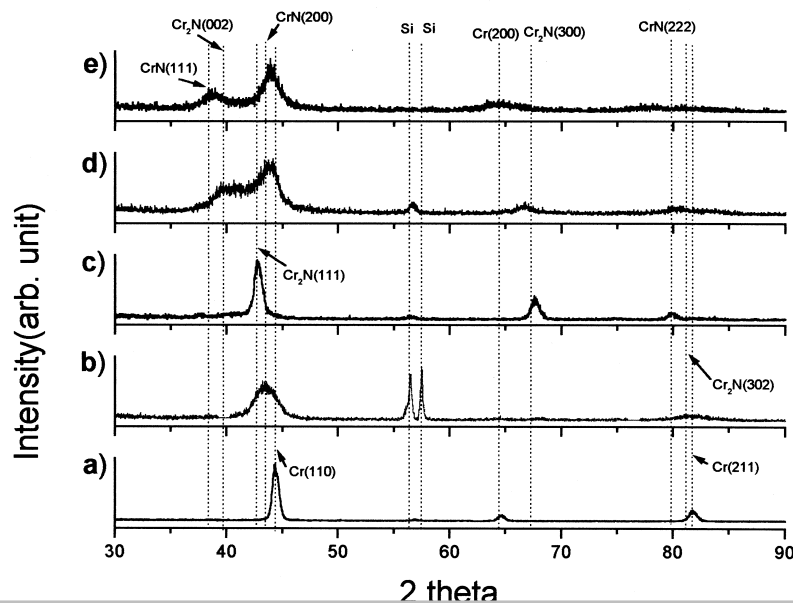
Deposition parameters	Conditions
Base pressure	3×10^{-5} torr
Ar pressure	1.8×10^{-3} torr
Target power density	13 ± 1 W/cm ² (DC)
Distance between target and substrate	80 mm
Temperature	$400 \pm 10^\circ\text{C}$
N ₂ flow rate	0 ~ 45 sccm
Substrate bias (pulsed DC)	
Voltage (V)	–50, –100, –200
Duty cycle (%)	50, 70, 100
Frequency (kHz)	5, 10, 20

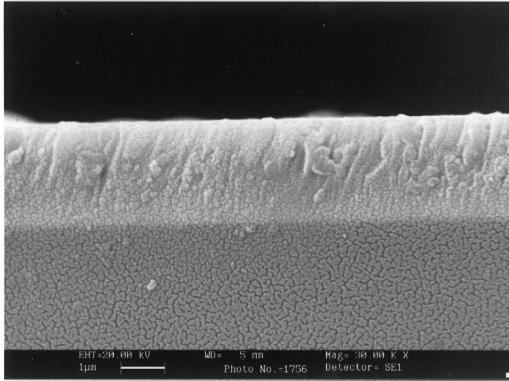
tional morphologies were investigated and the deposition rate of coated samples was calculated. Micro Knoop hardness was measured at a normal load of 0.025 N. The adhesion strength was compared by observing the propensity for cracks and the degree of delamination near the indentation periphery using an optical microscope after Rockwell C indentation test.

3. Results and discussion

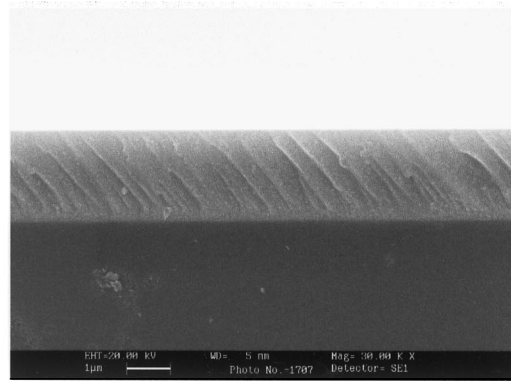
3.1. Influence of N₂ flow rate

Fig. 1 shows XRD patterns of CrN_x films deposited on Si wafer with various N₂ flow rates at a negative DC bias of –100 V. At a N₂ flow rate of 20 sccm, a mixed phase containing Cr(110), CrN(200) and Cr₂N(111) was observed. As N₂ flow rate is further increased upon

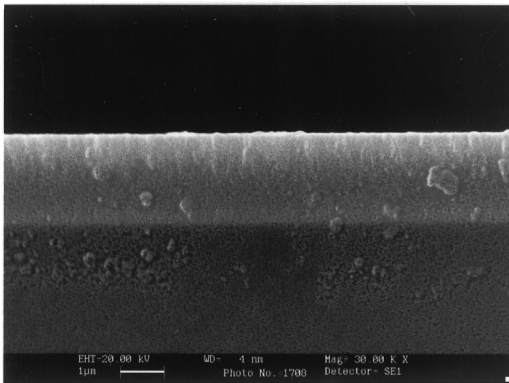




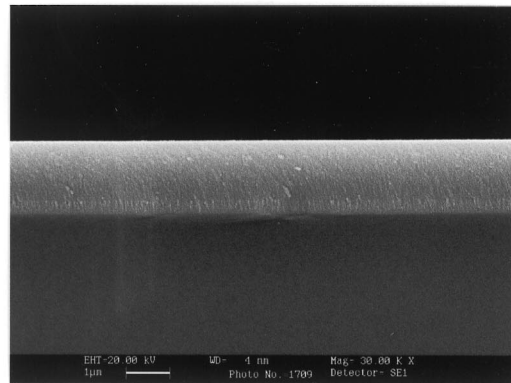
(a) Deposition rate : 236nm/min



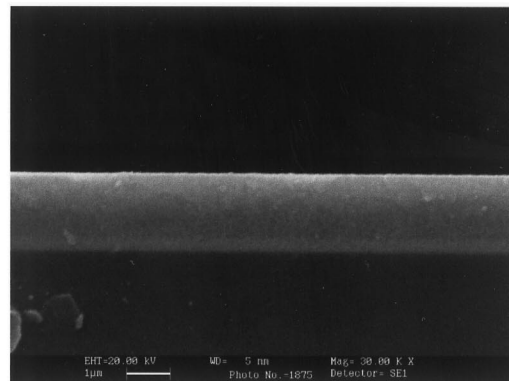
(b) Deposition rate : 204nm/min



(c) Deposition rate : 206nm/min



(d) Deposition rate : 165nm/min



(e) Deposition rate : 181nm/min

Fig. 2. Cross-sectional scanning electron micrographs of CrN_x films deposited on Si wafer with various N_2 flow rates. (a) 0 sccm, (b) 20 sccm, (c) 30 sccm, (d) 40 sccm and (e) 45 sccm.

deposition, CrN_x films tend to change from the hexagonal Cr_2N phase to the cubic CrN phase. The CrN_x film deposited with N_2 flow rate of 30 sccm was formed mostly with Cr_2N mono-phase and then transformed to

CrN mono-phase with a further increase of the N_2 flow to 45 sccm.

The SEM micrographs of fractured cross-sections of the films are illustrated in Fig. 2. It shows that the

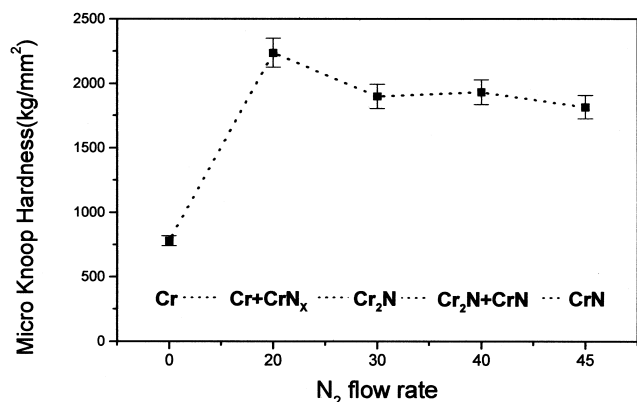


Fig. 3. Microhardness changes of CrN_x films measured at normal load of 0.025 N for various N₂ flow rates.

increasing of N₂ flow rate leads to an increase of film density and the decrease of its deposition rate from 236 to 165 nm/min except for CrN_x film deposited with a N₂ flow rate of 45 sccm. This reduction of deposition rate is due to the formation of chromium nitride at the target surface, the so called ‘poisoning effect’ [4,5].

Fig. 3 illustrates the microhardness of CrN_x films deposited with various N₂ flow rates. The maximum hardness value of 2250 kg/mm² was obtained for CrN_x film deposited with a N₂ flow rate of 20 sccm while further increase of the N₂ flow rate up to 45 sccm tended to reduce the hardness in the range of 1800–2000 kg/mm². These results are somewhat different from other reports in which the maximum hardness value was obtained for Cr₂N mono-phase [10,11]. It is estimated that the mixing effect [12] between Cr, Cr₂N and CrN plays a role to improve hardness of CrN_x film deposited with N₂ flow rate of 20 sccm. And also the reason why the similar hardness value was obtained for Cr₂N film deposited with N₂ flow rate of 30 sccm compared with CrN films is predicted that this film was consist of not only Cr₂N phases but also CrN phases as shown in Fig. 1.

After results of Rockwell C indentation adhesion tests, all CrN_x films deposited with various N₂ flow rates persisted in fairly good adhesion with a little crack and delamination corresponding to HF1 ~ HF3

in terms of the German short form of adhesion strength [13,14].

3.2. Influence of substrate bias

For the understanding of substrate bias effect influenced CrN_x film properties CrN_x films were deposited with various substrate bias voltage, duty cycle and frequency using pulsed DC power supply at constant N₂ flow rate of 40 sccm. Table 2 illustrates sample name and summary of the substrate bias effect on the deposition rate, microhardness and adhesion strength of CrN_x films. Moreover, the microstructure of each coated sample was identified in Fig. 4 by XRD analyses. The microstructure of CrN_x film deposited with a negative DC bias voltage of –100 V (CrN-2) was defined to be Cr₂N + CrN multi-phase. However, this multi-phase was changed to Cr₂N mono-phase (CrN-1, 3) when the substrate bias voltage was varied. Also, the variation of pulse frequency at a duty cycle of 70% led to the phase transformation from Cr₂N mono-phase (CrN-5) to Cr₂N + CrN multi-phase (CrN-4, 6), and then Cr₂N mono-phase (CrN-5) was changed to Cr₂N + CrN multi-phase (CrN-7) with the decrease of duty cycle at the same frequency. These phase transformations with the change of substrate bias is due to nearly equal energy of formation between Cr₂N (–122.88 kJ/mol) and CrN (–123.98 kJ/mol) at 400°C with constant N₂ partial pressure [10]. Two different phases, CrN and Cr₂N, which have very closed value of free energy of formation have almost same probability to nucleate and grow. Thus, these two phases might independently nucleate depending on the adatom energy state which is strongly influenced by substrate bias when other deposition parameters such as power density of target, substrate temperature and N₂ flow rate were the same.

At a negative bias voltage with sufficient duty cycle and frequency (CrN-5, 6), respectively, the deposition rate was increased. It is estimated that the ionization efficiency was increased by repetitive impact and stagnation between adatoms caused by a negative pulsed DC bias [15]. The maximum deposition rate of 210

Table 2
Sample identification and summary of the substrate bias effect

Sample	Duty cycle (%)	Frequency (kHz)	Bias voltage (V)	Deposition rate (nm/min)	Microhardness (kg/mm ²)	Adhesion strength
CrN-1	100	–	–50	174	1631	HF3 ~ 4
CrN-2	100	–	–100	165	1930	HF1 ~ 2
CrN-3	100	–	–200	194	2099	HF1 ~ 2
CrN-4	70	5	–100	162	2044	HF2 ~ 3
CrN-5	70	10	–100	210	2037	HF1 ~ 2
CrN-6	70	20	–100	180	2063	HF1 ~ 2
CrN-7	50	10	–100	163	1599	HF3 ~ 4

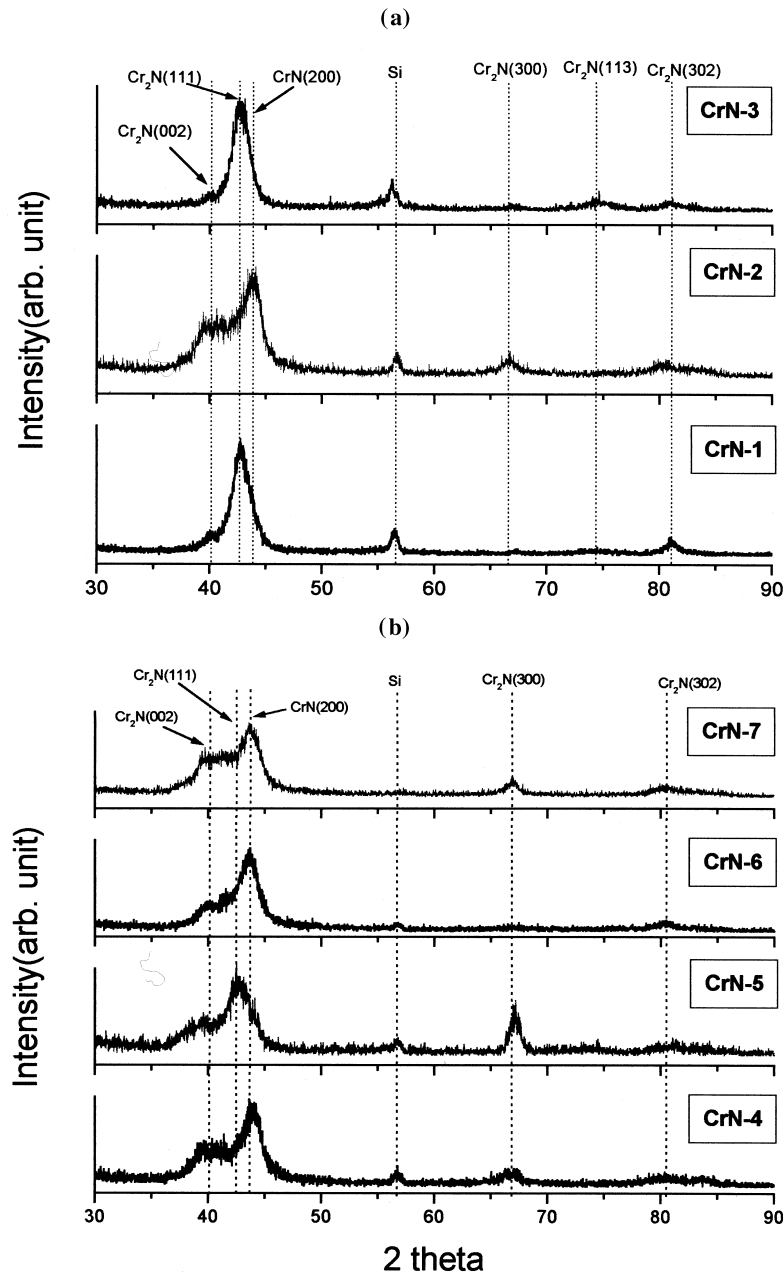


Fig. 4. XRD patterns of CrN_x films deposited on Si wafer at N₂ flow rate of 40 sccm with (a) various substrate bias voltages and (b) various substrate bias duty cycles and frequencies.

nm/min was obtained for CrN-5, which is 89% compared with the deposition rate of pure Cr coating under the same conditions except for a negative-pulsed DC duty cycle.

The microhardness of CrN_x films were measured to be similar values independent of the microstructure except for CrN-1 and CrN-7 which were deposited with low bias voltage or duty cycle. It has been reported [16,17] that the low bias voltage or duty cycle leads to a decrease of microhardness of films due to decreasing adatom mobility. After results of adhesion tests by Rockwell C indentation, CrN-1 and CrN-7 were found

to be HF3 ~ 4 while other films have a good adhesion strength corresponding to HF1 ~ 3. The low adhesion of CrN-1 and CrN-7 is understood by the decrease of ion bombardment caused by low adatom mobility during processes.

4. Summary

The high rate deposition of CrN_x films was carried

Explore Litigation Insights

Docket Alarm provides insights to develop a more informed litigation strategy and the peace of mind of knowing you're on top of things.

Real-Time Litigation Alerts



Keep your litigation team up-to-date with **real-time alerts** and advanced team management tools built for the enterprise, all while greatly reducing PACER spend.

Our comprehensive service means we can handle Federal, State, and Administrative courts across the country.

Advanced Docket Research



With over 230 million records, Docket Alarm's cloud-native docket research platform finds what other services can't. Coverage includes Federal, State, plus PTAB, TTAB, ITC and NLRB decisions, all in one place.

Identify arguments that have been successful in the past with full text, pinpoint searching. Link to case law cited within any court document via Fastcase.

Analytics At Your Fingertips



Learn what happened the last time a particular judge, opposing counsel or company faced cases similar to yours.

Advanced out-of-the-box PTAB and TTAB analytics are always at your fingertips.

API

Docket Alarm offers a powerful API (application programming interface) to developers that want to integrate case filings into their apps.

LAW FIRMS

Build custom dashboards for your attorneys and clients with live data direct from the court.

Automate many repetitive legal tasks like conflict checks, document management, and marketing.

FINANCIAL INSTITUTIONS

Litigation and bankruptcy checks for companies and debtors.

E-DISCOVERY AND LEGAL VENDORS

Sync your system to PACER to automate legal marketing.